

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3993	solder with indium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:35
L2	1022	1 and (heat with (conductive conduction sink spreader lid radiate radiating radiated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:36
L3	2809	1 and (substrate carrier board pcb ((printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:37
L4	2809	3 and (substrate carrier board pcb ((printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:37
L5	815	2 and (substrate carrier board pcb ((printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:37
L6	497	(overmold mod resin sealing seal encase encapsulating encapsulation encapsulate encapsulated) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:38

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6700195".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 01:16
L2	3993	solder with indium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 01:16
L3	2744	(semiconductor die chip dice ic (integrated adj circuit) flipchip (flip adj chip)) and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 01:18
L4	2165	(board pcb substrate ((printed circuit wring) adj4 board)) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 01:19
L5	1075	(overmold mold compound encapsulating encapsulation encapsulated encapsulated encase) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 01:20